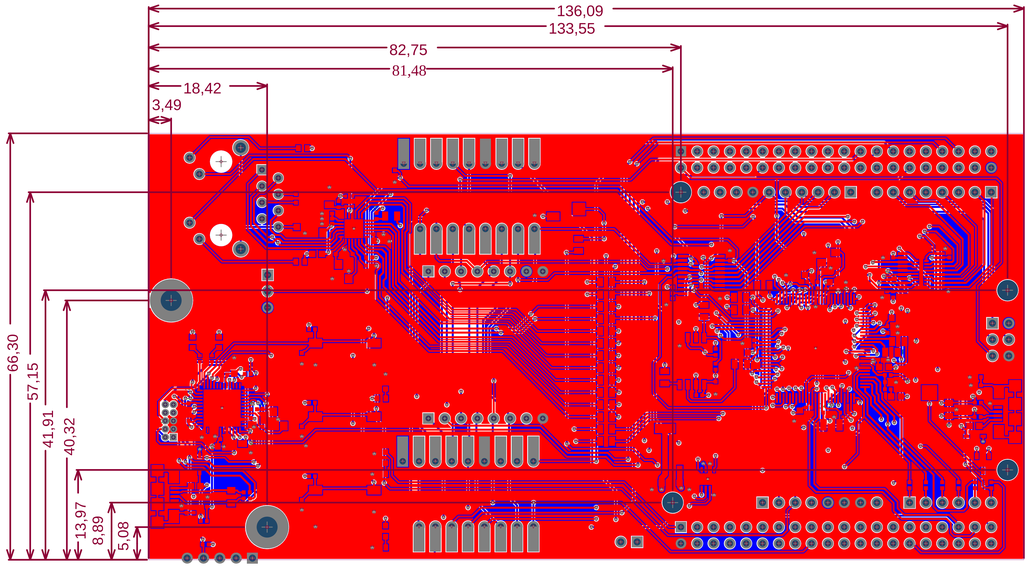

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
▽	388	0,300mm (11,81mil)	PTH	Round	L1_Top - L6_Bot	Via	Rounded
○	10	0,710mm (27,95mil)	PTH	Round	L1_Top - L6_Bot	Pad	(Mixed)
□	16	0,889mm (35,00mil)	PTH	Round	L1_Top - L6_Bot	Pad	(Mixed)
⊠	8	0,900mm (35,43mil)	PTH	Round	L1_Top - L6_Bot	Pad	(Mixed)
▽	34	1,000mm (39,37mil)	PTH	Round	L1_Top - L6_Bot	Pad	(Mixed)
⊠	84	1,020mm (40,16mil)	PTH	Round	L1_Top - L6_Bot	Pad	(Mixed)
☼	48	1,100mm (43,31mil)	PTH	Round	L1_Top - L6_Bot	Pad	(Mixed)
✪	2	1,600mm (62,99mil)	PTH	Round	L1_Top - L6_Bot	Pad	Rounded
▣	4	3,200mm (125,98mil)	NPTH	Round	L1_Top - L6_Bot	Pad	Rounded
◇	2	3,250mm (127,95mil)	NPTH	Round	L1_Top - L6_Bot	Pad	Rounded
◎	2	3,251mm (128,00mil)	NPTH	Round	L1_Top - L6_Bot	Pad	Rounded
	598 Total						

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ENGINEER:		TITLE: Platform2Go XMC4400-V1	
PCB DESIGNER: T. Lau			
DATE: 30.09.2019	PART NO.:	REL: RC02	REV: V1.1
SVN REVISION: Not In VersionControl	FILE NAME: Platform2Go XMC4400-V1_1.PcbDoc	APRV: R. B.	SCALE: 1:1

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